



Figure 181: Circuit configuration 1 schematic

**Note:** For PCB reference layouts, see the product page for the device on [www.nordicsemi.com](http://www.nordicsemi.com).

Designator	Value	Description	Footprint
C1, C2, C13	2.2 µF	Capacitor, X6T, ±20%, 2.5 V	0201
C5	N.C.	Not mounted	0201
C6, C9	1.2 pF	Capacitor, NPO, ±0.05 pF, 50 V	0201
C8, C11	100 nF	Capacitor, X7R, ±10%	0201
C10	10 µF	Capacitor, X6S, ±20%, 6.3 V	0402
C12	N.C.	Not mounted	0201
FB1, FB2	120 Ω	Ferrite bead, 120 Ω at 100 MHz, 200 mA, 500 mΩ Max	0201
L1	4.7 µH	Inductor, 300 mA, ±20%, 1.08 Ω	0402
L2, L3	4.7 nH	Inductor, 400 mA, ±3%, 250 mΩ	0201
L4	2.0 nH	Inductor, 600 mA, ±0.1 nH, 120 mΩ	0201
U1	nRF54L15-CAAA	Multiprotocol Bluetooth Low Energy, IEEE 802.15.4, and 2.4GHz proprietary System on Chip	CSP47
X1	32.768 kHz	Crystal SMD 2012, 32.768 kHz, Cl = 9 pF, Total tol: ±20 ppm	XTAL_2012
X2	32 MHz	Crystal SMD 1612, 32 MHz, Cl = 8 pF, Total Tol: ±40 ppm, Aging ±1 ppm/year. For frequency tolerance requirements, see <a href="#">32 MHz crystal oscillator (HFXO)</a> on page 902.	XTAL_1612

Table 89: Bill of material for circuit configuration 1

### 10.3.3 PCB layout example

The PCB layout in the following figure is a reference layout for Circuit configuration no. 1 for QFAA QFN48.